

IN THE CLAIMS:

Please amend Claims 1 and 20 as follows:

C1 1. (Twice Amended) A microelectronic spring structure, comprising:
a base formed of a resilient material;

a beam formed integrally with said base of said resilient material by depositing said resilient material in a uniform layer over a substrate, said beam comprising an elongated sheet of said resilient material cantilevered from said base along a path, said sheet having a substantially uniform thickness and upper and lower surfaces bounded by opposing edges, said opposing edges narrower than said upper and lower surfaces and defining widths of said beam perpendicular to said path; and

a tip positioned at a second end of said beam opposite to said base;

wherein said beam has an unsupported span between said tip and said base and every cross-section taken across a width of said unsupported span perpendicular to said path having opposite ends defined by said opposing edges has, for at least a length of said unsupported span, a portion of said sheet disposed a perpendicular distance from a neutral axis of said every cross-section substantially greater than one-half of said substantially uniform thickness of said sheet, said neutral axis running through a centroid of said every cross-section and disposed parallel to a line between said opposite ends of said every cross-section.

C2 20. (Twice Amended) The microelectronic spring structure of Claim 1, wherein said every cross-section at every location along said length of said unsupported span has a portion disposed a perpendicular distance from said neutral axis of said every cross-section substantially greater than one-half of said substantially uniform thickness of said sheet.